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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	24
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1718-e-ss

TABLE 1-2: PIC16(L)F1718 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RB1/AN10/C1IN3-/C2IN3-/ OPA2OUT	RB1	TTL/ST	CMOS	General purpose I/O.
	AN10	AN	—	ADC Channel 10 input.
	C1IN3-	AN	—	Comparator C1 negative input.
	C2IN3-	AN	—	Comparator C2 negative input.
	OPA2OUT	—	AN	Operational Amplifier 2 output.
RB2/AN8/OPA2IN-	RB2	TTL/ST	CMOS	General purpose I/O.
	AN8	AN	—	ADC Channel 8 input.
	OPA2IN-	AN	—	Operational Amplifier 2 inverting input.
RB3/AN9/C1IN2-/C2IN2-/ OPA2IN+	RB3	TTL/ST	CMOS	General purpose I/O.
	AN9	AN	—	ADC Channel 9 input.
	C1IN2-	AN	—	Comparator C1 negative input.
	C2IN2-	AN	—	Comparator C2 negative input.
	OPA2IN+	AN	—	Operational Amplifier 2 non-inverting input.
RB4/AN11	RB4	TTL/ST	CMOS	General purpose I/O.
	AN11	AN	—	ADC Channel 11 input.
RB5/AN13/T1G(1)	RB5	TTL/ST	CMOS	General purpose I/O.
	AN13	AN	—	ADC Channel 13 input.
	T1G	TTL/ST	—	Timer1 gate input.
RB6/CLCIN2(1)/ICSPCLK	RB6	TTL/ST	CMOS	General purpose I/O.
	CLCIN2	TTL/ST	—	Configurable Logic Cell source input.
	ICSPCLK	ST	—	Serial Programming Clock.
RB7/DAC1OUT2/DAC2OUT2/ CLCIN3(1)/ICSPDAT	RB7	TTL/ST	CMOS	General purpose I/O.
	DAC1OUT2	—	AN	Digital-to-Analog Converter output.
	DAC2OUT2	—	AN	Digital-to-Analog Converter output.
	CLCIN3	TTL/ST	—	Configurable Logic Cell source input.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
RC0/T1CKI(1)/SOSCO	RC0	TTL/ST	CMOS	General purpose I/O.
	T1CKI	TTL/ST	—	Timer1 clock input.
	SOSCO	XTAL	XTAL	Secondary Oscillator Connection.
RC1/SOSCI/CCP2(1)	RC1	TTL/ST	CMOS	General purpose I/O.
	SOSCI	XTAL	XTAL	Secondary Oscillator Connection.
	CCP2	TTL/ST	—	Capture input
RC2/AN14/CCP1(1)	RC2	TTL/ST	CMOS	General purpose I/O.
	AN14	AN	—	ADC Channel 14 input.
	CCP1	TTL/ST	—	Capture input
RC3/AN15/SCK(1)/SCL(1)	RC3	TTL/ST	CMOS	General purpose I/O.
	AN15	AN	—	ADC Channel 15 input.
	SCK	TTL/ST	—	SPI clock input
	SCL	I^2C	—	I^2C clock input.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C
HV = High Voltage XTAL = Crystal levels

Note 1: Default peripheral input. Alternate pins can be selected as the peripheral input with the PPS input selection registers.

2: All pin digital outputs default to PORT latch data. Alternate outputs can be selected as the peripheral digital output with the PPS output selection registers.

3: These peripheral functions are bidirectional. The output pin selections must be the same as the input pin selections.

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TABLE 3-7: PIC16(L)F1717 MEMORY MAP, BANK 24-31

BANK 24		BANK 25		BANK 26		BANK 27		BANK 28		BANK 29		BANK 30		BANK 31	
C00h	Core Registers (Table 3-2)	C80h	Core Registers (Table 3-2)	D00h	Core Registers (Table 3-2)	D80h	Core Registers (Table 3-2)	E00h	Core Registers (Table 3-2)	E80h	Core Registers (Table 3-2)	F00h	Core Registers (Table 3-2)	F80h	Core Registers (Table 3-2)
C0Bh		C8Bh		D0Bh		D8Bh		E0Bh		E8Bh		F0Bh		F8Bh	
C0Ch	—	C8Ch	—	D0Ch	—	D8Ch	—	E0Ch	See Table 3-9 for register mapping details	E8Ch	See Table 3-9 for register mapping details	F0Ch	See Table 3-9 for register mapping details	F8Ch	See Table 3-10 for register mapping details
C0Dh	—	C8Dh	—	D0Dh	—	D8Dh	—	E0Dh		E8Dh		F0Dh		F8Dh	
C0Eh	—	C8Eh	—	D0Eh	—	D8Eh	—	E0Eh		E8Eh		F0Eh		F8Eh	
C0Fh	—	C8Fh	—	D0Fh	—	D8Fh	—	E0Fh		E8Fh		F0Fh		F8Fh	
C10h	—	C90h	—	D10h	—	D90h	—	E10h		E90h		F10h		F90h	
C11h	—	C91h	—	D11h	—	D91h	—	E11h		E91h		F11h		F91h	
C12h	—	C92h	—	D12h	—	D92h	—	E12h		E92h		F12h		F92h	
C13h	—	C93h	—	D13h	—	D93h	—	E13h		E93h		F13h		F93h	
C14h	—	C94h	—	D14h	—	D94h	—	E14h		E94h		F14h		F94h	
C15h	—	C95h	—	D15h	—	D95h	—	E15h		E95h		F15h		F95h	
C16h	—	C96h	—	D16h	—	D96h	—	E16h		E96h		F16h		F96h	
C17h	—	C97h	—	D17h	—	D97h	—	E17h		E97h		F17h		F97h	
C18h	—	C98h	—	D18h	—	D98h	—	E18h		E98h		F18h		F98h	
C19h	—	C99h	—	D19h	—	D99h	—	E19h		E99h		F19h		F99h	
C1Ah	—	C9Ah	—	D1Ah	—	D9Ah	—	E1Ah		E9Ah		F1Ah		F9Ah	
C1Bh	—	C9Bh	—	D1Bh	—	D9Bh	—	E1Bh		E9Bh		F1Bh		F9Bh	
C1Ch	—	C9Ch	—	D1Ch	—	D9Ch	—	E1Ch		E9Ch		F1Ch		F9Ch	
C1Dh	—	C9Dh	—	D1Dh	—	D9Dh	—	E1Dh		E9Dh		F1Dh		F9Dh	
C1Eh	—	C9Eh	—	D1Eh	—	D9Eh	—	E1Eh		E9Eh		F1Eh		F9Eh	
C1Fh	—	C9Fh	—	D1Fh	—	D9Fh	—	E1Fh		E9Fh		F1Fh		F9Fh	
C20h	Unimplemented Read as '0'	CA0h	Unimplemented Read as '0'	D20h	Unimplemented Read as '0'	DA0h	Unimplemented Read as '0'	E20h		EA0h		F20h		FA0h	
C6Fh		CEFh		D6Fh		DEFh		E6Fh		EEFh		F6Fh		FEFh	
C70h	Accesses 70h – 7Fh	CF0h	Accesses 70h – 7Fh	D70h	Accesses 70h – 7Fh	DF0h	Accesses 70h – 7Fh	E70h	Accesses 70h – 7Fh	EF0h	Accesses 70h – 7Fh	F70h	Accesses 70h – 7Fh	FF0h	Accesses 70h – 7Fh
CFFh		CFFh		D7Fh		DFFh		E7Fh		EFFh		F7Fh		FFFh	

Legend: = Unimplemented data memory locations, read as '0'.

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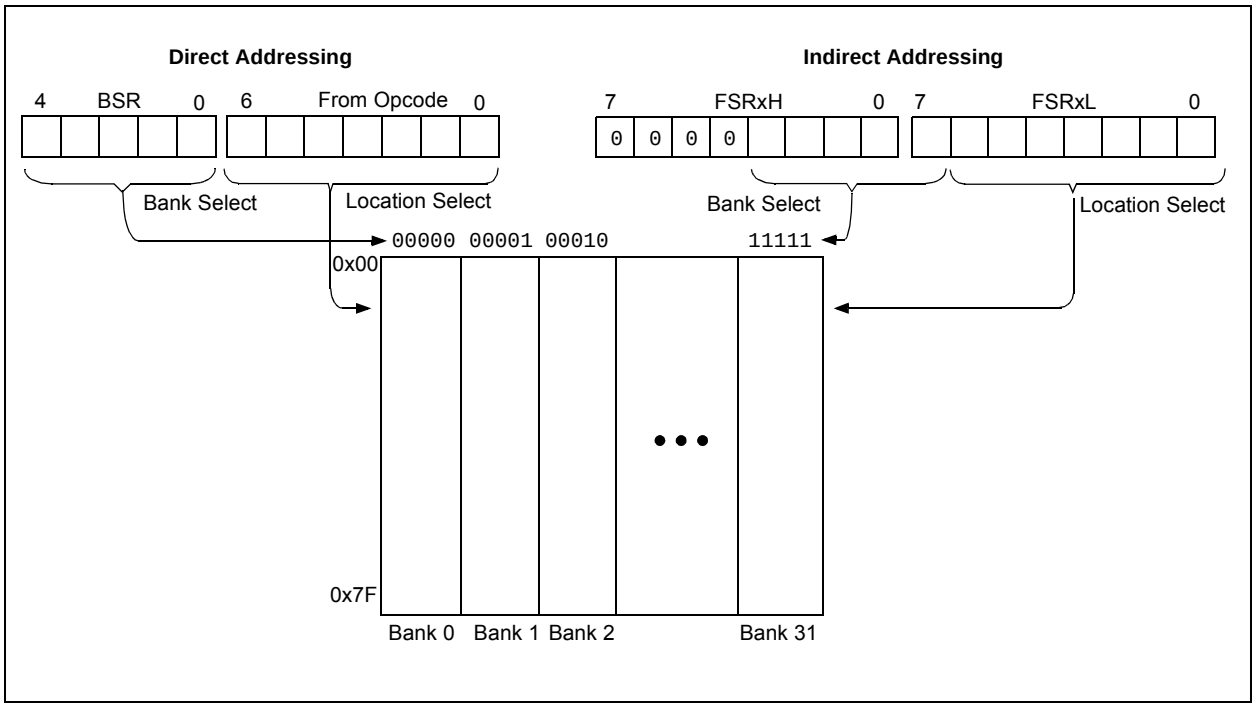
3.7.1 TRADITIONAL DATA MEMORY

The traditional data memory is a region from FSR address 0x000 to FSR address 0xFFF. The addresses correspond to the absolute addresses of all SFR, GPR and common registers.

FIGURE 3-10: TRADITIONAL DATA MEMORY MAP



5.0 RESETS

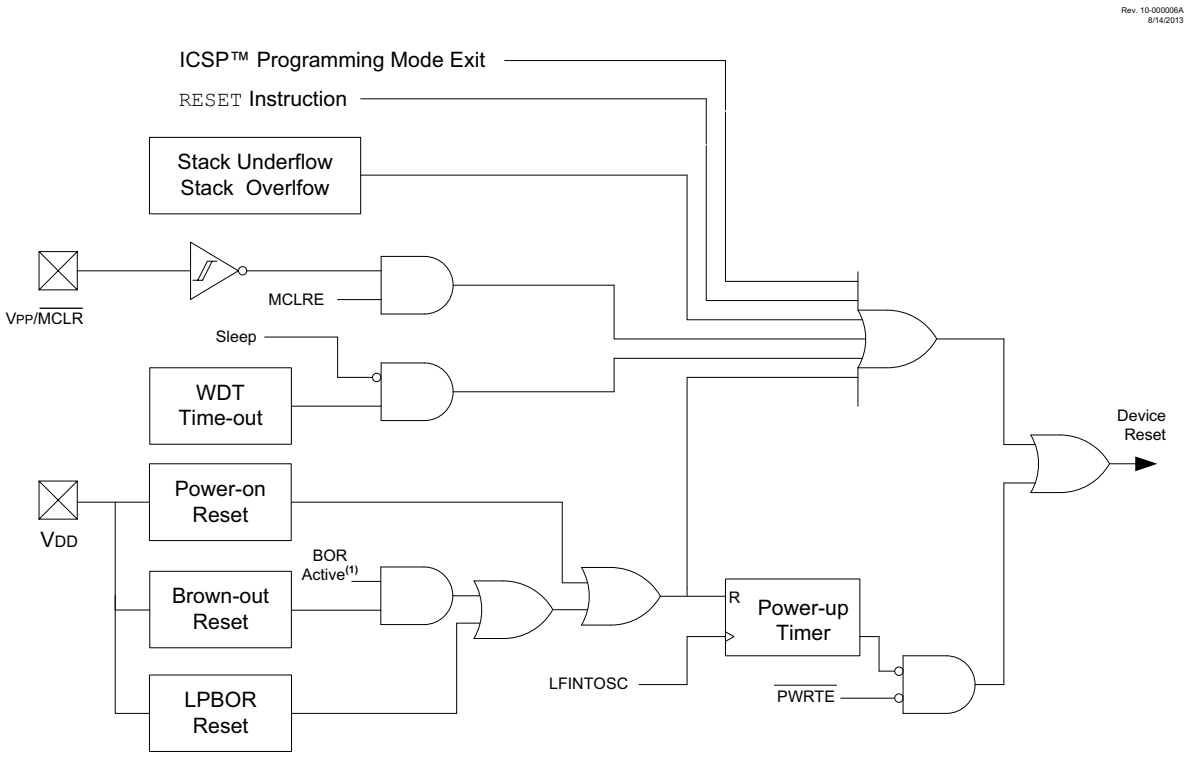
There are multiple ways to reset this device:

- Power-on Reset (POR)
- Brown-out Reset (BOR)
- Low-Power Brown-out Reset (LPBOR)
- MCLR Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional Power-up Timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: See Table 5-1 for BOR active conditions.

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6.2.2.5 Internal Oscillator Frequency Selection

The system clock speed can be selected via software using the Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register.

The postscaled output of the 16 MHz HFINTOSC, 500 kHz MFINTOSC, and 31 kHz LFINTOSC connect to a multiplexer (see Figure 6-1). The Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register select the frequency output of the internal oscillators. One of the following frequencies can be selected via software:

- 32 MHz (requires 4 x PLL)
- 16 MHz
- 8 MHz
- 4 MHz
- 2 MHz
- 1 MHz
- 500 kHz (default after Reset)
- 250 kHz
- 125 kHz
- 62.5 kHz
- 31.25 kHz
- 31 kHz (LFINTOSC)

Note:	Following any Reset, the IRCF<3:0> bits of the OSCCON register are set to '0111' and the frequency selection is set to 500 kHz. The user can modify the IRCF bits to select a different frequency.

The IRCF<3:0> bits of the OSCCON register allow duplicate selections for some frequencies. These duplicate choices can offer system design trade-offs. Lower power consumption can be obtained when changing oscillator sources for a given frequency. Faster transition times can be obtained between frequency changes that use the same oscillator source.

6.2.2.6 32 MHz Internal Oscillator Frequency Selection

The Internal Oscillator Block can be used with the 4x PLL associated with the External Oscillator Block to produce a 32 MHz internal system clock source. The following settings are required to use the 32 MHz internal clock source:

- The FOSC bits in Configuration Words must be set to use the INTOSC source as the device system clock (FOSC<2:0> = 100).
- The SCS bits in the OSCCON register must be cleared to use the clock determined by FOSC<2:0> in Configuration Words (SCS<1:0> = 00).
- The IRCF bits in the OSCCON register must be set to the 8 MHz HFINTOSC set to use (IRCF<3:0> = 1110).
- The SPLLEN bit in the OSCCON register must be set to enable the 4x PLL, or the PLLEN bit of the Configuration Words must be programmed to a '1'.

Note:	When using the PLLEN bit of the Configuration Words, the 4x PLL cannot be disabled by software and the SPLLEN option will not be available.

The 4x PLL is not available for use with the internal oscillator when the SCS bits of the OSCCON register are set to '1x'. The SCS bits must be set to '00' to use the 4x PLL with the internal oscillator.

FIGURE 6-7: INTERNAL OSCILLATOR SWITCH TIMING

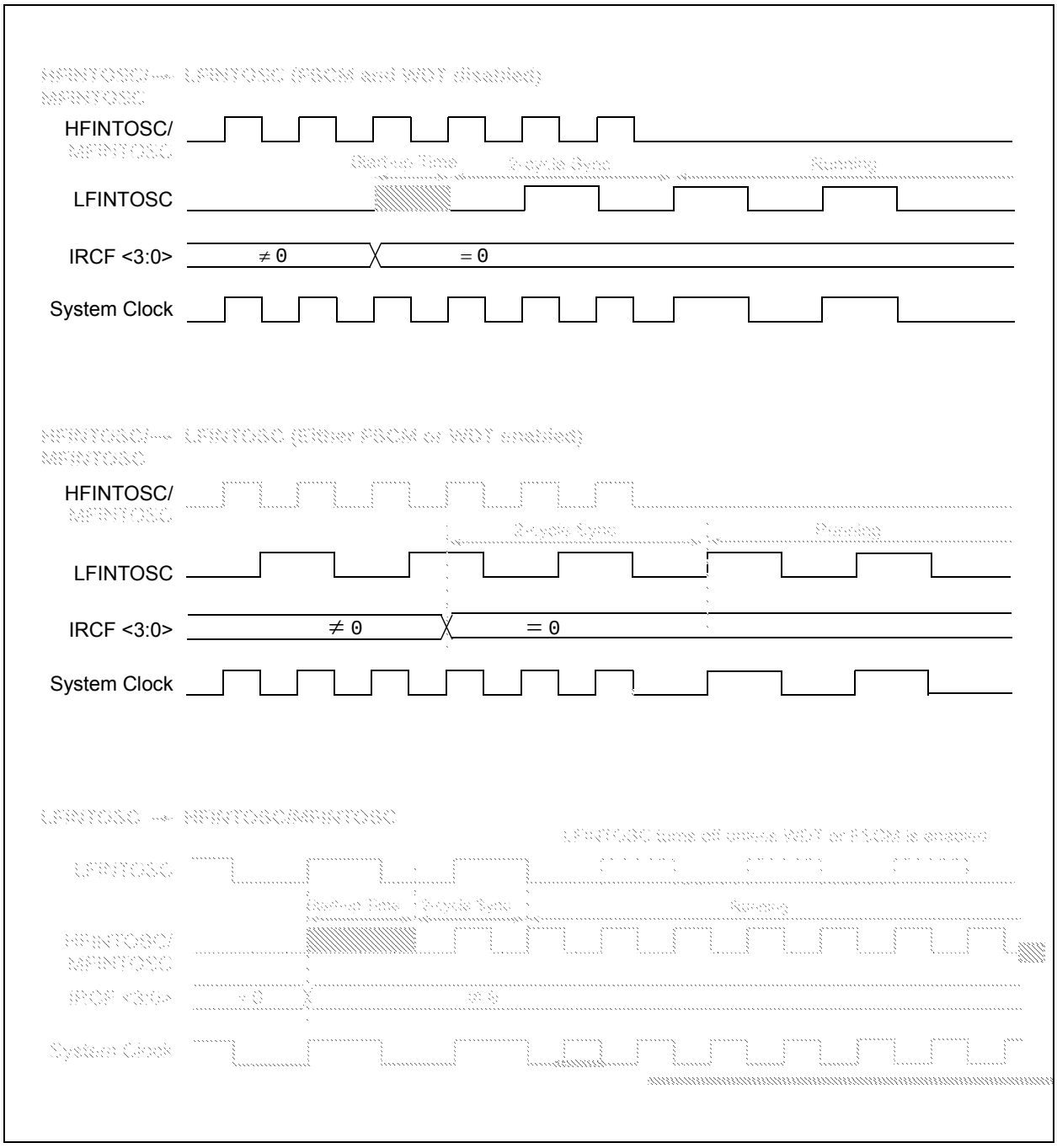
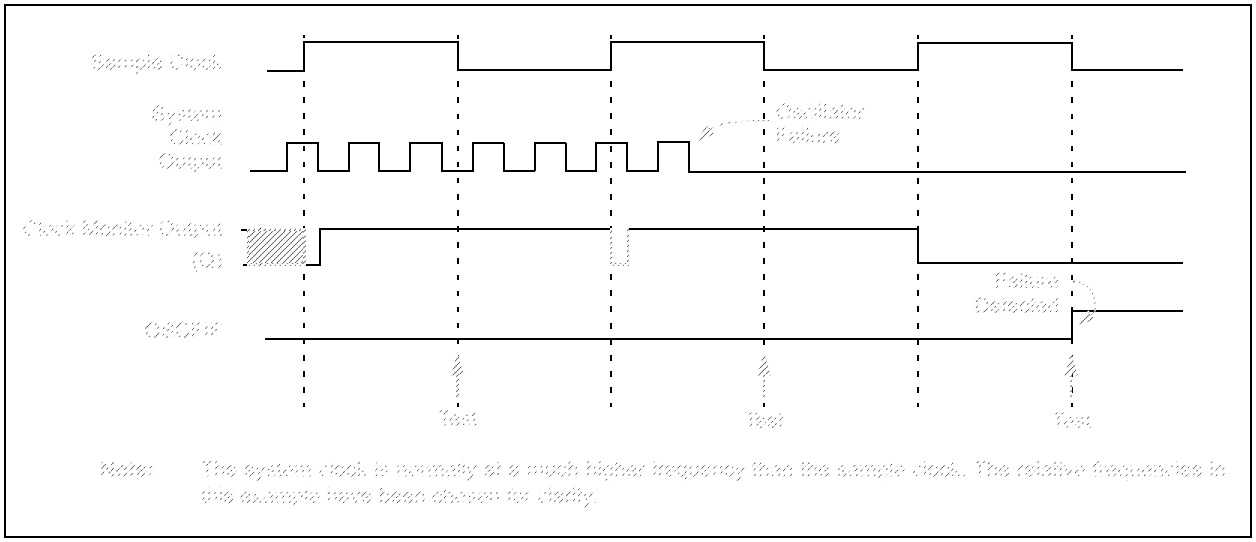


FIGURE 6-10: FSCM TIMING DIAGRAM



Note: The system clock is normally at a much higher frequency than the sample clock. The relative frequencies in this example have been chosen for clarity.

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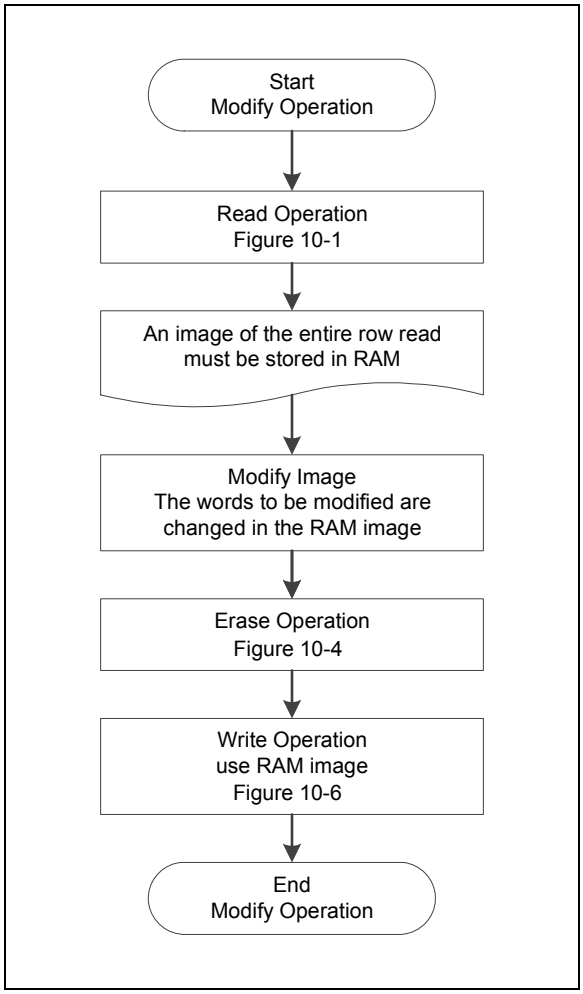
10.3 Modifying Flash Program Memory

When modifying existing data in a program memory row, and data within that row must be preserved, it must first be read and saved in a RAM image. Program memory is modified using the following steps:

1. Load the starting address of the row to be modified.
2. Read the existing data from the row into a RAM image.
3. Modify the RAM image to contain the new data to be written into program memory.
4. Load the starting address of the row to be rewritten.
5. Erase the program memory row.
6. Load the write latches with data from the RAM image.
7. Initiate a programming operation.

FIGURE 10-7: FLASH PROGRAM MEMORY MODIFY FLOWCHART



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REGISTER 18-14: COGxPHR: COG RISING EDGE PHASE DELAY COUNT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	GxPHR<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **GxPHR<5:0>:** Rising Edge Phase Delay Count Value bits
= Number of COGx clock periods to delay rising edge event

REGISTER 18-15: COGxPHF: COG FALLING EDGE PHASE DELAY COUNT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	GxPHF<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **GxPHF<5:0>:** Falling Edge Phase Delay Count Value bits
= Number of COGx clock periods to delay falling edge event

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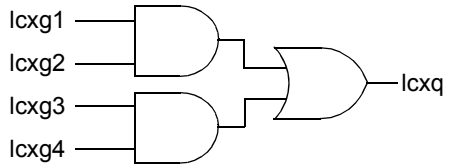
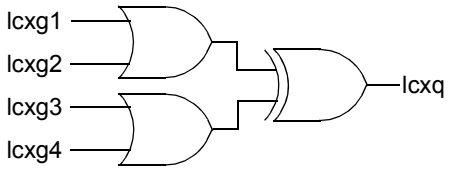
FIGURE 19-3: PROGRAMMABLE LOGIC FUNCTIONS

AND - OR



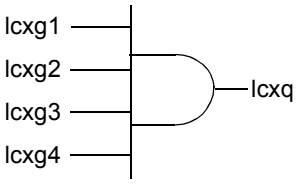
LCxMODE<2:0>= 000

OR - XOR



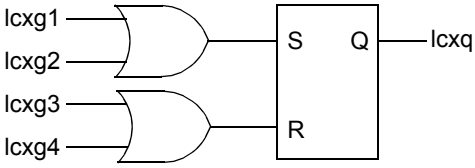
LCxMODE<2:0>= 001

4-Input AND



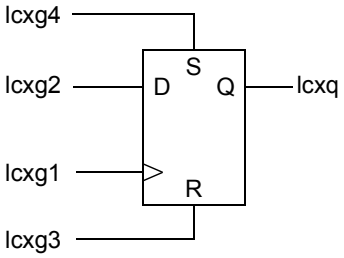
LCxMODE<2:0>= 010

S-R Latch



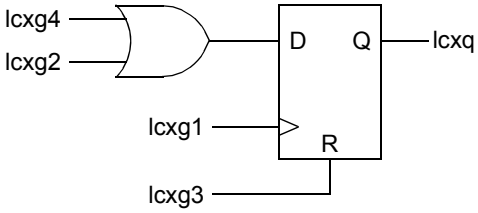
LCxMODE<2:0>= 011

1-Input D Flip-Flop with S and R



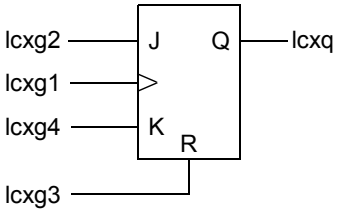
LCxMODE<2:0>= 100

2-Input D Flip-Flop with R



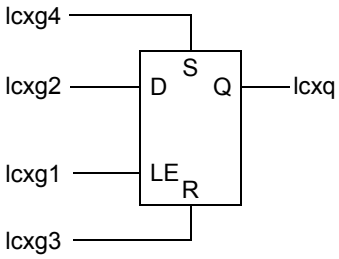
LCxMODE<2:0>= 101

J-K Flip-Flop with R



LCxMODE<2:0>= 110

1-Input Transparent Latch with S and R



LCxMODE<2:0>= 111

REGISTER 19-10: CLCxGLS3: GATE 4 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG4D4T	LCxG4D4N	LCxG4D3T	LCxG4D3N	LCxG4D2T	LCxG4D2N	LCxG4D1T	LCxG4D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **LCxG4D4T:** Gate 4 Data 4 True (non-inverted) bit
1 = LCxD4T is gated into LCxG4
0 = LCxD4T is not gated into LCxG4

bit 6 **LCxG4D4N:** Gate 4 Data 4 Negated (inverted) bit
1 = LCxD4N is gated into LCxG4
0 = LCxD4N is not gated into LCxG4

bit 5 **LCxG4D3T:** Gate 4 Data 3 True (non-inverted) bit
1 = LCxD3T is gated into LCxG4
0 = LCxD3T is not gated into LCxG4

bit 4 **LCxG4D3N:** Gate 4 Data 3 Negated (inverted) bit
1 = LCxD3N is gated into LCxG4
0 = LCxD3N is not gated into LCxG4

bit 3 **LCxG4D2T:** Gate 4 Data 2 True (non-inverted) bit
1 = LCxD2T is gated into LCxG4
0 = LCxD2T is not gated into LCxG4

bit 2 **LCxG4D2N:** Gate 4 Data 2 Negated (inverted) bit
1 = LCxD2N is gated into LCxG4
0 = LCxD2N is not gated into LCxG4

bit 1 **LCxG4D1T:** Gate 4 Data 1 True (non-inverted) bit
1 = LCxD1T is gated into LCxG4
0 = LCxD1T is not gated into LCxG4

bit 0 **LCxG4D1N:** Gate 4 Data 1 Negated (inverted) bit
1 = LCxD1N is gated into LCxG4
0 = LCxD1N is not gated into LCxG4

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FIGURE 24-1: DIGITAL-TO-ANALOG CONVERTER BLOCK DIAGRAM

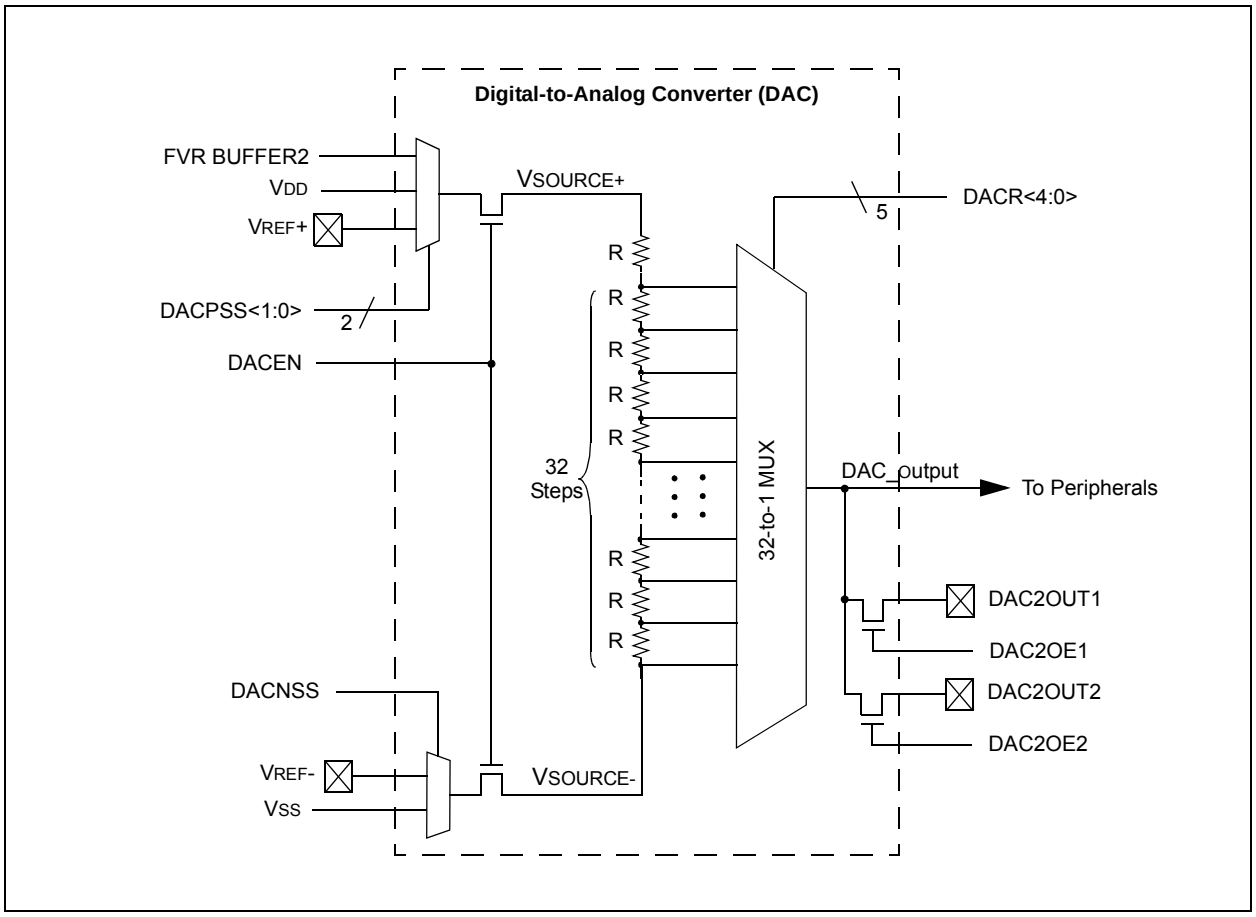
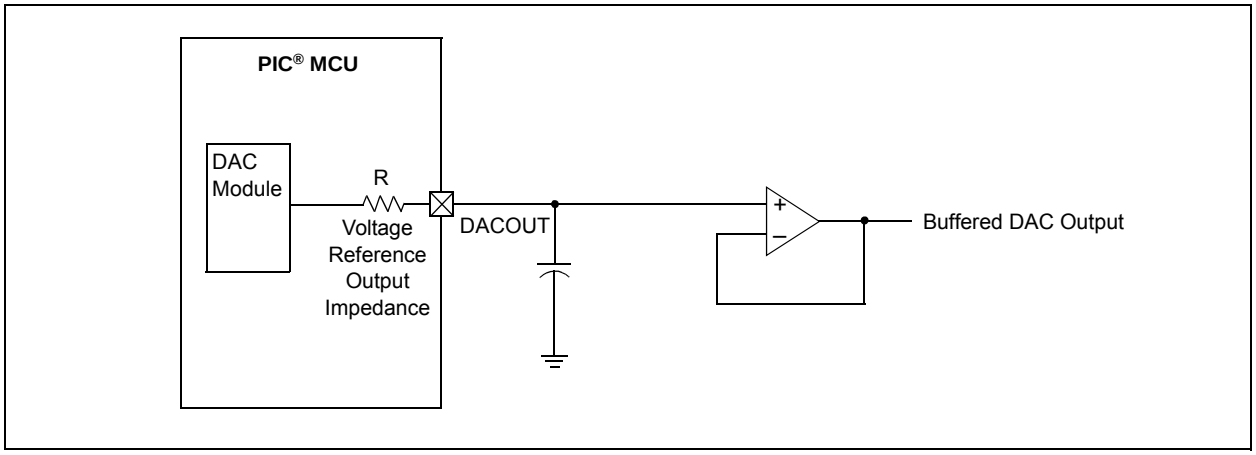


FIGURE 24-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



24.4 Operation During Sleep

When the device wakes up from Sleep through an interrupt or a Watchdog Timer time-out, the contents of the DAC2CON0 register are not affected. To minimize current consumption in Sleep mode, the voltage reference should be disabled.

24.5 Effects of a Reset

A device Reset affects the following:

- DAC is disabled
- DAC output voltage is removed from the DAC2OUTx pin
- The DAC2R<4:0> range select bits are cleared

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25.2 ZCD Logic Output

The ZCD module includes a Status bit, which can be read to determine whether the current source or sink is active. The ZCDxOUT bit of the ZCDxCON register is set when the current sink is active, and cleared when the current source is active. The ZCDxOUT bit is affected by the polarity bit.

25.3 ZCD Logic Polarity

The ZCDxPOL bit of the ZCDxCON register inverts the ZCDxOUT bit relative to the current source and sink output. When the ZCDxPOL bit is set, a ZCDxOUT high indicates that the current source is active, and a low output indicates that the current sink is active.

The ZCDxPOL bit affects the ZCD interrupts. See **Section 25.4 "ZCD Interrupts"**.

25.4 ZCD Interrupts

An interrupt will be generated upon a change in the ZCD logic output when the appropriate interrupt enables are set. A rising edge detector and a falling edge detector are present in the ZCD for this purpose.

The ZCDIF bit of the PIR3 register will be set when either edge detector is triggered and its associated enable bit is set. The ZCDxINTP enables rising edge interrupts and the ZCDxINTN bit enables falling edge interrupts. Both are located in the ZCDxCON register.

To fully enable the interrupt, the following bits must be set:

- ZCDIE bit of the PIE3 register
- ZCDxINTP bit of the ZCDxCON register (for a rising edge detection)
- ZCDxINTN bit of the ZCDxCON register (for a falling edge detection)
- PEIE and GIE bits of the INTCON register

Changing the ZCDxPOL bit will cause an interrupt, regardless of the level of the ZCDxEN bit.

The ZCDIF bit of the PIR3 register must be cleared in software as part of the interrupt service. If another edge is detected while this flag is being cleared, the flag will still be set at the end of the sequence.

25.5 Correcting for ZCPINV Offset

The actual voltage at which the ZCD switches is the reference voltage at the non-inverting input of the ZCD op amp. For external voltage source waveforms other than square waves this voltage offset from zero causes the zero-cross event to occur either too early or too late. When the waveform is varying relative to Vss then the zero cross is detected too early as the waveform falls and too late as the waveform rises. When the waveform is varying relative to VDD then the zero cross is detected too late as the waveform rises and too early as the waveform falls. The actual offset time can be determined for sinusoidal waveforms with the corresponding equations shown in Equation 25-2.

EQUATION 25-2: ZCD EVENT OFFSET

When External Voltage Source is relative to Vss:

$$T_{offset} = \frac{\text{asin}\left(\frac{Z_{cpinv}}{V_{peak}}\right)}{2\pi \bullet Freq}$$

When External Voltage Source is relative to VDD:

$$T_{offset} = \frac{\text{asin}\left(\frac{VDD - Z_{cpinv}}{V_{peak}}\right)}{2\pi \bullet Freq}$$

This offset time can be compensated for by adding a pull-up or pull-down biasing resistor to the ZCD pin. A pull-up resistor is used when the external voltage source is varying relative to Vss. A pull-down resistor is used when the voltage is varying relative to VDD.The resistor adds a bias to the ZCD pin so that the target external voltage source must go to zero to pull the pin voltage to the ZCPINV switching voltage. The pull-up or pull-down value can be determined with the equations shown in Equation 25-3.

EQUATION 25-3: ZCD PULL-UP/DOWN

When External Signal is relative to Vss:

$$R_{pullup} = \frac{R_{series}(V_{pullup} - Z_{cpinv})}{Z_{cpinv}}$$

When External Signal is relative to VDD:

$$R_{pulldown} = \frac{R_{series}(Z_{cpinv})}{(VDD - Z_{cpinv})}$$

The pull-up and pull-down resistor values are significantly affected by small variations of ZCPINV. Measuring ZCPINV can be difficult, especially when the waveform is relative to VDD. However, by combining Equation 25-2 and Equation 25-3 the resistor value

30.5.3.3 7-Bit Transmission with Address Hold Enabled

Setting the AHEN bit of the SSP1CON3 register enables additional clock stretching and interrupt generation after the eighth falling edge of a received matching address. Once a matching address has been clocked in, CKP is cleared and the SSP1IF interrupt is set.

Figure 30-19 displays a standard waveform of a 7-bit address slave transmission with AHEN enabled.

1. Bus starts Idle.
2. Master sends Start condition; the S bit of SSP1STAT is set; SSP1IF is set if interrupt on Start detect is enabled.
3. Master sends matching address with R/$\overline{W}$ bit set. After the eighth falling edge of the SCL line the CKP bit is cleared and SSP1IF interrupt is generated.
4. Slave software clears SSP1IF.
5. Slave software reads ACKTIM bit of SSP1CON3 register, and R/$\overline{W}$ and D/$\overline{A}$ of the SSP1STAT register to determine the source of the interrupt.
6. Slave reads the address value from the SSP1BUF register clearing the BF bit.
7. Slave software decides from this information if it wishes to $\overline{ACK}$ or not $\overline{ACK}$ and sets the ACKDT bit of the SSP1CON2 register accordingly.
8. Slave sets the CKP bit releasing SCL.
9. Master clocks in the $\overline{ACK}$ value from the slave.
10. Slave hardware automatically clears the CKP bit and sets SSP1IF after the $\overline{ACK}$ if the R/$\overline{W}$ bit is set.
11. Slave software clears SSP1IF.
12. Slave loads value to transmit to the master into SSP1BUF setting the BF bit.

Note: SSP1BUF cannot be loaded until after the $\overline{ACK}$.

13. Slave sets the CKP bit releasing the clock.
14. Master clocks out the data from the slave and sends an $\overline{ACK}$ value on the 9th SCL pulse.
15. Slave hardware copies the $\overline{ACK}$ value into the ACKSTAT bit of the SSP1CON2 register.
16. Steps 10-15 are repeated for each byte transmitted to the master from the slave.
17. If the master sends a not $\overline{ACK}$ the slave releases the bus allowing the master to send a Stop and end the communication.

Note: Master must send a not $\overline{ACK}$ on the last byte to ensure that the slave releases the SCL line to receive a Stop.

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31.1.2.4 Receive Framing Error

Each character in the receive FIFO buffer has a corresponding framing error Status bit. A framing error indicates that a Stop bit was not seen at the expected time. The framing error status is accessed via the FERR bit of the RC1STA register. The FERR bit represents the status of the top unread character in the receive FIFO. Therefore, the FERR bit must be read before reading the RC1REG.

The FERR bit is read-only and only applies to the top unread character in the receive FIFO. A framing error (FERR = 1) does not preclude reception of additional characters. It is not necessary to clear the FERR bit. Reading the next character from the FIFO buffer will advance the FIFO to the next character and the next corresponding framing error.

The FERR bit can be forced clear by clearing the SPEN bit of the RC1STA register which resets the EUSART. Clearing the CREN bit of the RC1STA register does not affect the FERR bit. A framing error by itself does not generate an interrupt.

Note:	If all receive characters in the receive FIFO have framing errors, repeated reads of the RC1REG will not clear the FERR bit.

31.1.2.5 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before the FIFO is accessed. When this happens the OERR bit of the RC1STA register is set. The characters already in the FIFO buffer can be read but no additional characters will be received until the error is cleared. The error must be cleared by either clearing the CREN bit of the RC1STA register or by resetting the EUSART by clearing the SPEN bit of the RC1STA register.

31.1.2.6 Receiving 9-Bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RC1STA register is set the EUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RC1STA register is the ninth and Most Significant data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RC1REG.

31.1.2.7 Address Detection

A special Address Detection mode is available for use when multiple receivers share the same transmission line, such as in RS-485 systems. Address detection is enabled by setting the ADDEN bit of the RC1STA register.

Address detection requires 9-bit character reception. When address detection is enabled, only characters with the ninth data bit set will be transferred to the receive FIFO buffer, thereby setting the RCIF interrupt bit. All other characters will be ignored.

Upon receiving an address character, user software determines if the address matches its own. Upon address match, user software must disable address detection by clearing the ADDEN bit before the next Stop bit occurs. When user software detects the end of the message, determined by the message protocol used, software places the receiver back into the Address Detection mode by setting the ADDEN bit.

Note: Unless otherwise noted, VIN = 5V, FOSC = 500 kHz, CIN = 0.1 µF, TA = 25°C.

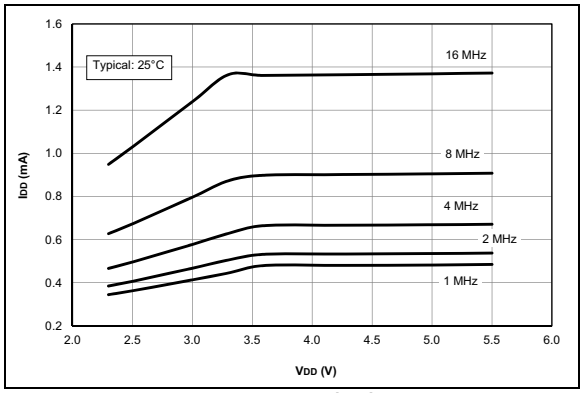


FIGURE 35-25: *IDD Typical, HFINTOSC Mode, PIC16F1717/8/9 Only.*

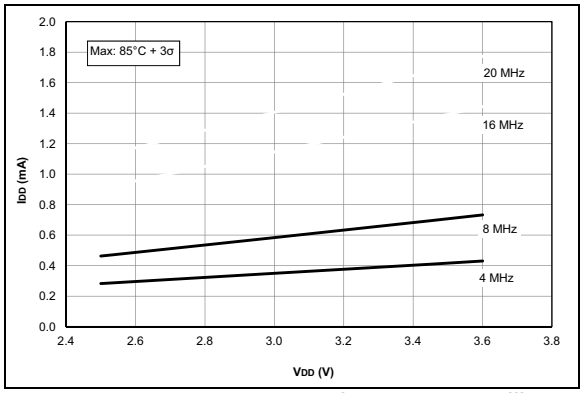


FIGURE 35-28: *IDD Maximum, HS Oscillator, PIC16LF1717/8/9 Only.*

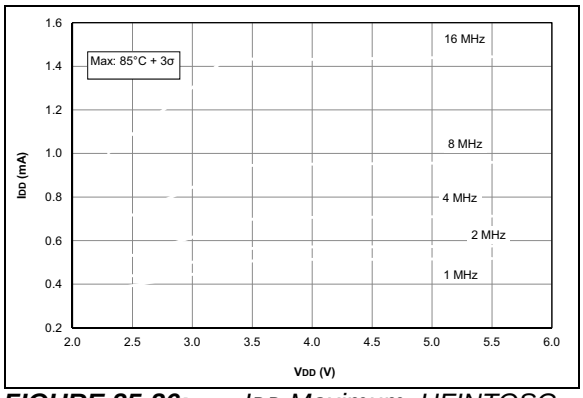


FIGURE 35-26: *IDD Maximum, HFINTOSC Mode, PIC16F1717/8/9 Only.*

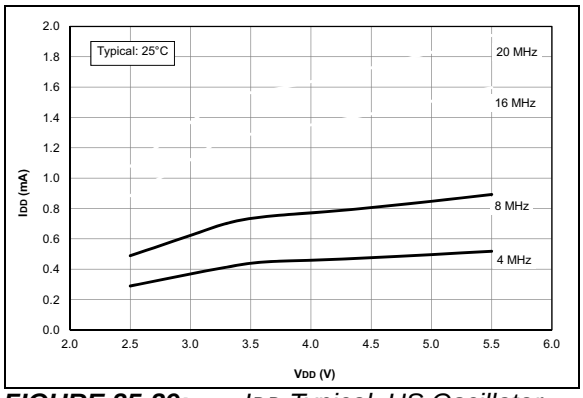


FIGURE 35-29: *IDD Typical, HS Oscillator, 25°C, PIC16F1717/8/9 Only.*

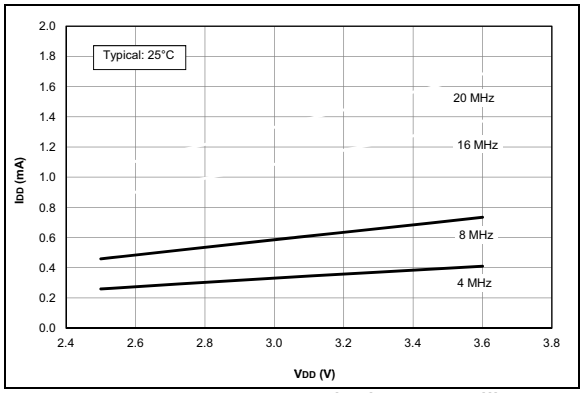


FIGURE 35-27: *IDD Typical, HS Oscillator, 25°C, PIC16LF1717/8/9 Only.*

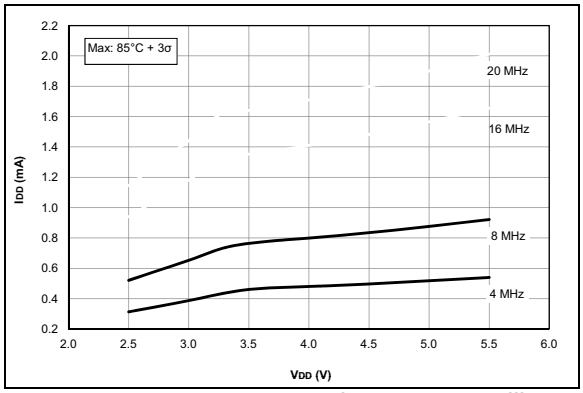
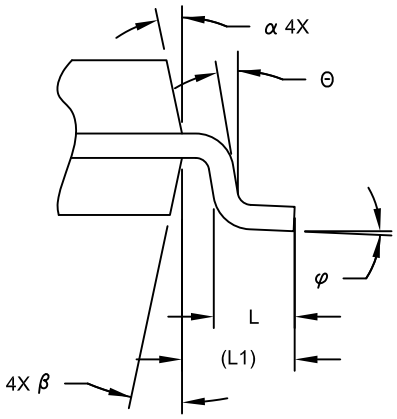


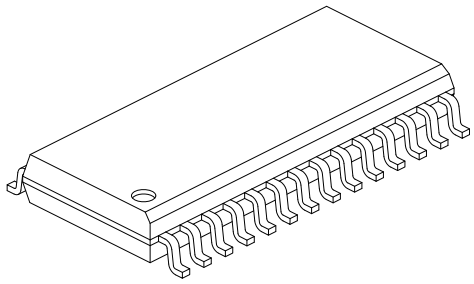
FIGURE 35-30: *IDD Maximum, HS Oscillator, PIC16F1717/8/9 Only.*

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

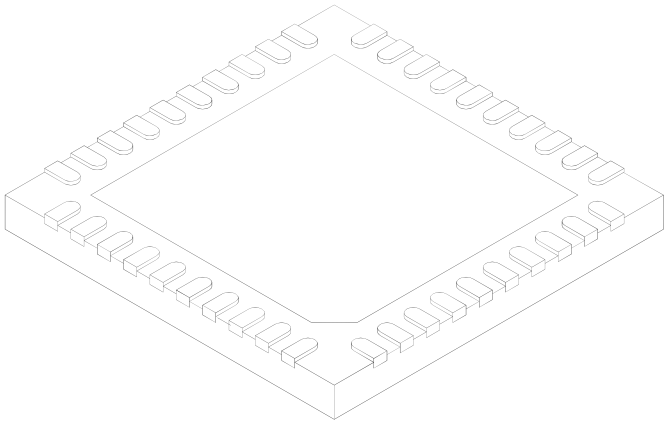
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

40-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) – 5x5x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.70	3.80
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.70	3.80
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-156A Sheet 2 of 2

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (02/2014)

Initial release of the document.

Revision B (12/2015)

Chapter 18.0 COG rewritten.

Added High-endurance Flash Data Memory information to cover pages and Memory chapter. Added Section 11.3.1 heading. Added Section 6.3.5: Clock Switching Before Sleep.

Deleted Section 24.4: Low-Power Voltage State.

Updated the Family Types Table and the Product Identification System page.

Updated Examples 3-2 and 21-; Figures 16-2, 18-2, 18-3, 18-4, 18-5, 18-6, 21-1, 22-1, 23-1, 24-1, 27-1, 29-2 and 29-4; Registers 11-8, 11-16, 11-24, 11-32, 11-40, 21-2, 22-1, 23-1, 23-2 and 30-4; Sections 3.3.2, 8.2.2, 11.9.1, 11.9.2, 18.1.1, 18.1.2,18.1.3, 18-1-4, 18-1.6, 18.2, 18.3.2, 18.3.3, 18.5, 18.5.4, 18.5.5, 18.8.3, 18.10, 20.0, 21.1.3, 22.0, 22.1, 22.1.1, 23.5, 24.0, 24.1, 24.3, 24.4, 24.5, 25.2, 25.8, 30.6, 31.6.2 and 34-1; Tables 3-10, 3-12, 6-1, 12-1, 16-3, 17-3, 21-3, 24-1, 34-1, 34-2, 34-3, 34-4, 34-5, 34-8, 34-11 and 34-24.

Minor typos corrected.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16F1717, PIC16LF1717, PIC16F1718, PIC16LF1718 PIC16F1719, PIC16LF1719	
Tape and Reel Option:	Blank T	= Standard packaging (tube or tray) = Tape and Reel(1)
Temperature Range:	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package:(2)	MV MV MM P PT SO SP SS	= UQFN, 28-lead 4x4x0.5mm = UQFN, 40-lead 5x5x0.5mm = QFN-S, 28-lead 6x6x0.9mm = PDIP, 40-lead = TQFP, 44-lead 10x10x1mm = SOIC, 28-lead = SPDIP, 28-lead = SSOP, 28-lead
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC16LF1717- I/P
Industrial temperature
PDIP package

b) PIC16F1718- E/SS
Extended temperature,
SSOP package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: Small form-factor packaging options may be available. Please check www.microchip.com/packaging for small-form factor package availability, or contact your local Sales Office.